

SSC Series



- IGBT based solid-state relay
- Ratings up to 25A @ 1,000 VDC
- DC control

PRODUCT SELECTION

| 25A | 25A |
|-----------|------------|
| SSC800-25 | SSC1000-25 |

OUTPUT SPECIFICATIONS (1)

| Description | 800 VDC | 1000 VDC |
|--|---------|----------|
| Operating Voltage [VDC] | 0-800 | 0-1000 |
| MaxImumTransient Overvoltage [Vpk] | 900(4) | 1200(5) |
| Maximum Off-State Leakage Current @ Rated Voltage [mA] | 0.3 | 0.3 |
| Maximum Load Current (3) [Adc] | 25 | 25 |
| Minimum Load Current [mA] | 20 | 20 |
| Maximum Surge Current [Adc] (10ms) | 75 | 75 |
| Maximum On-State Voltage Drop @ Rated Current [Vdc] | 1.6 | 1.6 |
| Thermal Resistance Junction to Case (Rjc) [°C/W] | 0.8 | 0.8 |

INPUT SPECIFICATIONS (1)

| Description | Suffix -12 | Suffix -24 | Suffix -36 |
|--|------------|------------|------------|
| Nominal Control Voltage (6) | 12 VDC | 24 VDC | 36 VDC |
| Control Voltage Range | 8-16 VDC | 20-28 VDC | 32-40 VDC |
| Minimum Turn-On Voltage (7) | 8 VDC | 20 VDC | 32 VDC |
| Minimum Turn-Off Voltage | 1.0 VDC | 1.0 VDC | 1.0 VDC |
| Typical Input Current at Nominal Voltage | 15 mA | 15 mA | 15 mA |
| Nominal Input Impedance | 780 Ohm | 1500 Ohm | 2400 Ohm |
| Maximum Turn-On Time [msec] | 1.5 | 1.5 | 1.5 |
| Maximum Turn-Off Time [msec] | 1.5 | 1.5 | 1.5 |

GENERAL SPECIFICATIONS

| Description | Parameters |
|---|---|
| Dielectric Strength, Input/Output/Base (50/60Hz)(2) | 2500 VRMS |
| Minimum Insulation Resistance (@ 500 V DC)(2) | 10 ⁹ Ohm |
| Maximum Capacitance, Input/Output | 50 pF |
| Ambient Operating Temperature Range | -30 to 80°C |
| Ambient Storage Temperature Range | -40 to 125 °C |
| Weight (typical) | 3.0 oz (86.5g) |
| Encapsulation | Thermally conductive Epoxy |
| Terminals Screws and Saddle Clamps Furnished, Unmounted | |
| Recommended Terminal Screw Torque Range: | 6-32 Screws - 10 in lbs. 8-32 -20 in. lbs. (Screws dry without grase) |

GENERAL NOTES

- 1) All parameters at 25°C unless otherwise specified.
- 2) Dielectric strength and insulation resistance are measured between input and output
- 3) Heat sinking required, for derating curves see next page.
- 4) Internal overvoltage protection included.
- 5) Internal overvoltage protection not included.
- 6) Use suffix -12, -24 or -36 to specify control voltage. For other values call factory Sample: SSC800-25-24
- 7) Operation below the specified minimum turn-on voltage may result in linear operation of the output and damage to the relay.

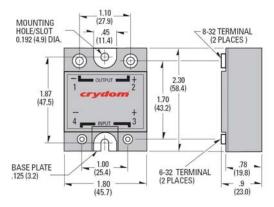


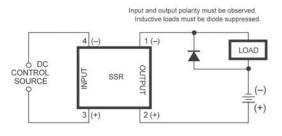
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Darta Panel Mount

MECHANICAL SPECIFICATIONS

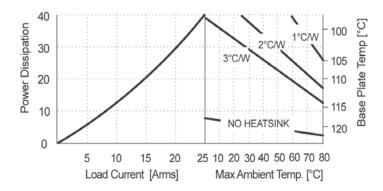




Transient Protection

All loads are inductive, even ones that are not so labeled. An inductive load will produce harmful transient voltages when it is turned off. The more perfect the switch, the larger the transient voltages; the MOSFET output is so nearly an ideal switch that the transient voltages produced by seemingly "non-inductive" loads can cause damage if not suppressed. Diodes should be fast recovery type with PIV rated greater than supply voltage.

THERMAL DERATE INFORMATION



AGENCY APPROVALS

Rev. 112210



| HAZARD OF ELECTRIC SHOCK, EXPLOSION, OR ARC FLASH. • Disconnect all power before installing or working with this equipment. • Verify all connections and replace all covers before turning on | RIESGO DE DESCARGA ELECTRICA O EXPLOSION. • Desconectar todos los suministros de energia a este equipo antes de trabajar con este equipo. • Verificar todas las conexiones y colocar todas las tapas antes | RISQUE DE DESCHARGE ELECTRIQUE OU EXPLOSION • Eteindre toutes les sources d'énergie de cet appareil avant de travailler dessus de cet appareil • Vérifier tous connections, et | ER /GEFAHR / PI GEFAHR EINES ELEKTRISCHE N SCHLAGES ODER EINER EXPLOSION. • Stellen Sie jeglichen Strom ab, der dieses Gerät versorgt, bevor Sie an dem Gerät Arbeiten durchführen • Vor der Inbetriebnahme alle Anschlüsse | ERICOLO / PERIO RISCHIO DI SCOSSA ELETTRICA O DELL'ESPLOSI ONE. • Spenga tutta l'alimentazion e che fornisce questa apparecchiatu ra prima del lavorare a questa apparecchiatu ra • Verificare tutti i collegamenti | RISCO DE DESCARGA ELÉTTRICA OU EXPLOSÃO • Desconectar o equipamento de toda á energia antes de instalar ou trabalhar com este equipamen to • Verificar todas as conexões e recolocar todas |
|---|--|--|---|--|--|
| | | y colocar todas las tapas antes de energizer el equipo. El incumplimiento de estas instrucciones puede provocar la muerte o lesiones serias. • Vérifier tous connections, et remettre tous couverts en olace avant de mettre sous De non-suivi de ces instructions provoquera la mort ou des sérieuses. | Inbetriebnahme | | |

Darta Panel Mount

| | SEMENT / WARNUNG /ADVERTENC | CIA / AVVERTENZA / AVISO | | |
|--|---|--|--|--|
| RISK OF MATERIAL DAMAGE AND HOT ENCLOSURE | RISQUE DE DOMMAGE MATERIEL ET DE SURCHAUFFE DU BOITIER | GEFAHR VON MATERIALSCHÄDEN UND GEHÄUSEERHITZUNG | | |
| The product's side panels may be hot, allow the product to cool before touching. Follow proper mounting instructions including torque values. Do not allow liquids or foreign objects to enter this product. | Les panneaux latéraux du produit peuvent être chauds. Laisser le produit refroidir avant de le toucher. Respecter les consignes de montage, et notamment les couples de serrage. Ne pas laisser pénétrer de liquide ni de corps étrangers à l'intérieur du produit. | Die Seitenwände können heiß sein. Lassen Sie das Produkt abkühlen, bevor Sie es berühren. Beachten Sie die Montageanweisungen, Führen Sie keine Flüssigkeiten oder Fremdkörper in das Produkt ein. | | |
| Failure to follow these instructions can result in serious injury, or equipment damage. | Le non-respect de cette directive peut entraîner, des lésions corporelles graves ou des dommages matériels. | Die Nichtbeachtung dieser Anweisung kann Körperverletzung oder Materialschäden zur Folge haben. | | |
| RIESGO DE DAÑOS MATERIALES Y DE SOBRECALENTAMIENTO DE LA UNIDAD | RISCHIO DI DANNI MATERIALI E D'INVOLUCRO CALDO | RISCO DE DANO MATERIAL E DE AQUECIMENTO | | |
| Los paneles laterales del producto pueden estar calientes. Esperar que el producto se enfrie antes de tocarlo. Respetar las instrucciones de montaje, y en particular los pares de apretado. No dejar que penetren líquidos o cuerpos extraños en el producto. | I pannelli laterali dell'apparecchio possono scottare; lasciar quindi raffreddare il prodotto prima di toccarlo. Seguire le istruzioni di montaggio corrette. Non far entrare liquidi o oggetti estranei in questo apparecchio. | Os painéis laterais do produto podem estar quentes; dê tempo ao produto para arrefecer antes de lhe tocar. Siga devidamente as instruções de montagem. Não permita a entrada de líquidos e de objectos estranhos no produto. | | |
| Si no se respetan estas precauciones pueden producirse graves lesiones, daños materiales. | La mancata osservanza di questa precauzione può causare gravi rischi per l'incolumità personale o danni alle apparecchiature. | A não observância destas precauções pode provocar a morte, ferimentos graves ou danos materiais. | | |



crydom



ANNEX - ENVIROMENTAL INFORMATION

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People's Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

| | Toxic or hazardous Substance and Elements | | | | | |
|-------------------|---|-----------------|-----------------|-------------------------------------|--------------------------------------|---|
| Part Name | Lead (Pb) | Mercury (Hg) | Cadmium (Cd) | Hexavalent Chromium (Cr (VI)) | Polybrominated biphenyls (PBB) | Polybrominated diphenyl ethers (PBDE) |
| Semiconductor die | х | 0 | 0 | 0 | 0 | 0 |
| Solder | X | 0 | 0 | 0 | 0 | 0 |

此附件所标示的包括电子信息产品污染图标的环保信息 符合中华人民共和国电子行业标准 SJ/T11364 - 2006, 电子信息产品污染控制标识要求



| 2017/11 | 有毒有害物质或元素 | | | | | |
|----------|-----------|-----------|-----------|------------------|---------------|-----------------|
| 部件 名称 | 铅 (Pb) | 汞 (Hg) | 镉 (Cd) | 六价铬 (Cr (VI)) | 多溴联苯 (PBB) | 多溴二苯醚 (PBDE) |
| 半导体芯片 | x | 0 | 0 | 0 | о | 0 |
| 焊接点 | X | 0 | 0 | 0 | 0 | 0 |

